Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.011”**

****

**.010”**

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size = .0035 x .0035”**

**Backside Potential: Collector**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .010” X .011” DATE: 3/27/23**

**MFG: SILICON SUPPLIES THICKNESS .007” P/N: 2N3906**

**DG 10.1.2**

#### Rev B, 7/1